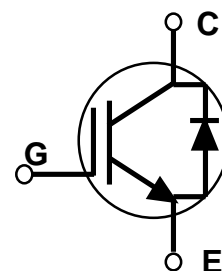


**SGL160N60UFD****CO-PAK IGBT****FEATURES**

- \* High Speed Switching
- \* Low Saturation Voltage  
:  $V_{CE(sat)} = 2.0\text{ V}$  (@  $I_C=80\text{A}$ )
- \* High Input Impedance
- \* CO-PAK, IGBT with FRD  
:  $T_{rr} = 50\text{nS}$  (typ.)

**APPLICATIONS**

- \* AC & DC Motor controls
- \* General Purpose Inverters
- \* Robotics , Servo Controls
- \* Power Supply

**TO-264****ABSOLUTE MAXIMUM RATINGS**

Symbol	Characteristics	Rating	Units
$V_{CES}$	Collector-Emitter Voltage	600	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_c = 25^\circ\text{C}$	160	A
	Collector Current @ $T_c = 100^\circ\text{C}$	80	A
$I_{CM(1)}$	Pulsed Collector Current	220	A
$I_F$	Diode Continuous Forward Current @ $T_c = 100^\circ\text{C}$	25	A
$I_{FM}$	Diode Maximum Forward Current	280	A
$P_D$	Maximum Power Dissipation @ $T_c = 25^\circ\text{C}$	200	W
	Maximum Power Dissipation @ $T_c = 100^\circ\text{C}$	80	W
$T_j$	Operating Junction Temperature	$-55 \sim 150$	$^\circ\text{C}$
$T_{stg}$	Storage Temperature Range	$-55 \sim 150$	$^\circ\text{C}$
$T_L$	Maximum Lead Temp. For Soldering	300	$^\circ\text{C}$
	Purposes, 1/8" from case for 5 seconds		

**Notes:**(1) Repetitive rating : Pulse width limited by max. junction temperature

## ELECTRICAL CHARACTERISTICS (IGBT PART)

(T<sub>c</sub>=25°C, Unless Otherwise Specified)

Symbol	Characteristics	Test Conditions	Min	Typ	Max	Units
BV <sub>CES</sub>	C - E Breakdown Voltage	V <sub>GE</sub> = 0V , I <sub>C</sub> = 250uA	600	-	-	V
ΔV <sub>CES</sub> / ΔT <sub>J</sub>	Temperature Coeff. of Breakdown Voltage	V <sub>GE</sub> = 0V , I <sub>C</sub> = 1mA	-	0.6	-	V/°C
V <sub>GE(th)</sub>	G - E threshold voltage	I <sub>C</sub> = 80mA , V <sub>CE</sub> = V <sub>GE</sub>	4.5	5.5	7.5	V
I <sub>CES</sub>	Collector cutoff Current	V <sub>CE</sub> = V <sub>CES</sub> , V <sub>GE</sub> = 0V	-	-	250	uA
I <sub>GES</sub>	G - E leakage Current	V <sub>GE</sub> = V <sub>GES</sub> , V <sub>CE</sub> = 0V	-	-	100	nA
V <sub>CE(sat)</sub>	Collector to Emitter saturation voltage	I <sub>C</sub> =80A, V <sub>GE</sub> = 15V	-	2.0	-	V
		I <sub>C</sub> =160A, V <sub>GE</sub> = 15V	-	2.6	-	V
Cies	Input capacitance	V <sub>GE</sub> = 0V , f = 1MHz V <sub>CE</sub> = 30V	-	5440	-	pF
Coes	Output capacitance		-	715	-	pF
Cres	Reverse transfer capacitance		-	184	-	pF
td(on)	Turn on delay time	V <sub>CC</sub> = 300V , I <sub>C</sub> = 80A V <sub>GE</sub> = 15V R <sub>G</sub> = 3.9Ω Inductive Load	-	24	-	ns
tr	Turn on rise time		-	54	-	ns
td(off)	Turn off delay time		-	95	-	ns
tf	Turn off fall time		-	100	-	ns
Eon	Turn on Switching Loss		-	0.12	-	mJ
Eoff	Turn off Switching Loss		-	0.19	-	mJ
Ets	Total Switching Loss		-	0.8	-	mJ
Qg	Total Gate Charge	V <sub>CC</sub> = 300V	-	344	517	nC
Qge	Gate-Emitter Charge	V <sub>GE</sub> = 15V	-	76	116	nC
Qgc	Gate-Collector Charge	I <sub>C</sub> = 80A	-	86	130	nC

**SGL160N60UFD****CO-PAK IGBT****ELECTRICAL CHARACTERISTICS (DIODE PART)**(T<sub>c</sub>=25°C, Unless Otherwise Specified)

Symbol	Characteristics	Test Conditions		Min	Typ	Max	Units
V <sub>FM</sub>	Diode Forward Voltage	I <sub>F</sub> =25A	T <sub>C</sub> =25°C	-	1.4	1.7	V
			T <sub>C</sub> =100°C	-	1.3	-	
T <sub>rr</sub>	Diode Reverse Recovery Time	I <sub>F</sub> =25A, V <sub>R</sub> =200V  -di/dt=200A/uS	T <sub>C</sub> =25°C	-	50	75	nS
			T <sub>C</sub> =100°C	-	105	-	
I <sub>rr</sub>	Diode Peak Reverse Recovery Current		T <sub>C</sub> =25°C	-	4.5	10	A
			T <sub>C</sub> =100°C	-	8.5	-	
Q <sub>rr</sub>	Diode Reverse Recovery Charge		T <sub>C</sub> =25°C	-	112	375	nC
			T <sub>C</sub> =100°C	-	420	-	

**THERMAL RESISTANCE**

Symbol	Characteristics	Min	Typ	Max	Units
R <sub>θJC</sub>	Junction-to-Case (IGBT)	-	-	0.625	°C/W
R <sub>θJC</sub>	Junction-to-Case (DIODE)	-	-	0.83	°C/W
R <sub>θJA</sub>	Junction-to-Ambient	-	-	25	°C/W
R <sub>θCS</sub>	Case-to-Sink	-	0.2	-	°C/W

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